



TPD2E2U06 2 チャネル高速 ESD 保護デバイス

1 特長

- IEC 61000-4-2 レベル 4
 - ±25kV (接触放電)
 - ±30kV (エアギャップ放電)
- IEC 61000-4-5 サージ保護
 - 5.5A ピーク・パルス電流 (8/20μs のパルス)
- IO 容量: 1.5pF (標準値)
- DC 降伏電圧: 6.5V (最小値)
- 非常に低いリーク電流: 10nA (最大値)
- 低い ESD クランプ電圧
- 産業用温度範囲: -40°C ~ +125°C
- 小型で配線が容易な DRL および DCK パッケージ

2 アプリケーション

- 最終製品
 - セット・トップ・ボックス
 - ノート PC
 - サーバー
 - 電子 POS (EPOS)
- インターフェイス
 - USB 2.0
 - イーサネット
 - MIPI バス
 - LVDS
 - I2C

3 概要

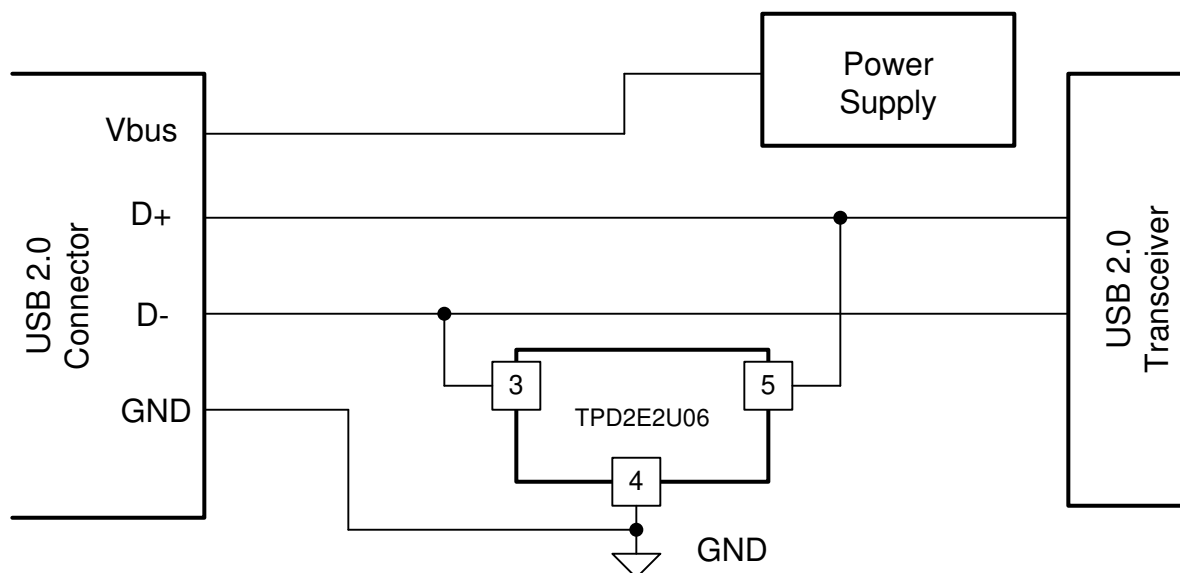
TPD2E2U06 はデュアル・チャネルの低容量 TVS ダイオード ESD 保護デバイスです。IEC 61000-4-2 規格に準拠し、接触で ±25kV、エアギャップで ±30kV の ESD 保護を実現します。TPD2E2U06 は、ライン容量が 1.5pF であるため、幅広いアプリケーションに適しています。代表的なアプリケーション・インターフェイスは USB 2.0、LVDS、I²C™ です。

製品情報⁽¹⁾

型番	パッケージ	本体サイズ(公称)
TPD2E2U06DRL	SOT (5)	1.60mm×1.20mm
TPD2E2U06DCK	SC70 (3)	2.0mm × 1.25mm

(1) 提供されているすべてのパッケージについては、巻末の注文情報を参照してください。

概略回路図



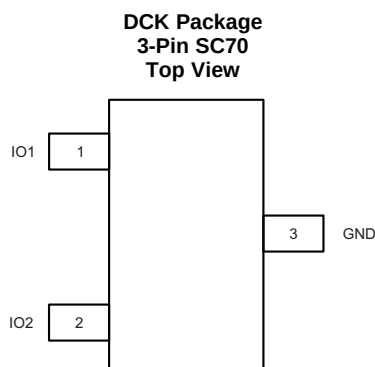
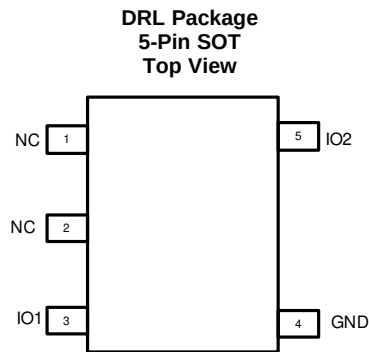
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4 改訂履歴

Revision B (May 2015) から Revision C に変更	Page
• Added DCK Package to the Pin Configuration and Functions section	3
• Added DCK Package to the Electrical Characteristics table	4
Revision A (June 2013) から Revision B に変更	Page
• 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを 追加	1

5 Pin Configuration and Functions



Pin Functions

PIN			I/O	DESCRIPTION
NAME	DRL	DCK		
IO1	3	1	I/O	The IO1 and IO2 pins are an ESD protected channel. Connect these pins to the data line as close to the connector as possible.
IO2	5	2	I/O	
NC	1, 2	—	-	This pin is not connected and is left floating, grounded, or connected to VCC.
GND	4	3	G	The GND (ground) pin is connected to ground.

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)

	MIN	MAX	UNIT
I_{PP} Peak pulse current ($t_p = 8/20 \mu s$)		5.5 ⁽¹⁾	A
P_{PP} Peak pulse power ($t_p = 8/20 \mu s$) DRL package		85 ⁽¹⁾	W
P_{PP} Peak pulse power ($t_p = 8/20 \mu s$) DCK package		75 ⁽¹⁾	W
Operating temperature	–40	125	°C
Storage temperature	–65	155	°C

(1) Measured at 25°C.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD) Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±4000	V
	Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1500	
	EC 61000-4-2 contact	±25000	
	EC 61000-4-2 air-gap	±30000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 500-V HBM is possible with the necessary precautions.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Manufacturing with less than 250-V CDM is possible with the necessary precautions.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{IO}	Input Pin Voltage	0		5.5	V
T _A	Operating Free Air Temperature	-40		125	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPD2E2U06		UNIT
		DRL	DCK	
		5 PINS	3 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	286.8	308.3	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	130.7	170.7	
R _{θJB}	Junction-to-board thermal resistance	104.8	89.2	
ψ _{JT}	Junction-to-top characterization parameter	25.6	34.2	
ψ _{JB}	Junction-to-board characterization parameter	104.3	88.6	

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics application report](#).

6.5 Electrical Characteristics

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{RWM}	Reverse stand-off voltage	I _{IO} < 10 μA			5.5	V
V _{CLAMP}	IO to GND	I _{PP} = 1 A, TLP ⁽¹⁾		9.7		V
		I _{PP} = 5 A, TLP ⁽¹⁾		12.4		
V _{CLAMP}	GND to IO	I _{PP} = 1 A, TLP ⁽¹⁾		1.9		V
		I _{PP} = 5 A, TLP ⁽¹⁾		4		
R _{DYN}	Dynamic resistance DRL package	IO to GND ⁽²⁾		0.5		Ω
R _{DYN}	Dynamic resistance DRL package	GND to IO ⁽²⁾		0.25		Ω
R _{DYN}	Dynamic resistance DCK package	IO to GND ⁽²⁾		0.6		Ω
R _{DYN}	Dynamic resistance DCK package	GND to IO ⁽²⁾		0.4		Ω
CL	Line capacitance	f = 1 MHz, V _{BIAS} = 2.5 V ⁽³⁾		1.5	1.9	pF
C _{CROSS}	Channel-to-channel input capacitance	Pin 4 = 0 V, f = 1 MHz, V _{BIAS} = 2.5 V, between channel pins ⁽³⁾		0.02	0.03	pF

- (1) Transmission Line Pulse with 10-ns rise time, 100-ns width.
- (2) Extraction of R_{DYN} Using least squares fit of TLP characteristics between I = 20 A and I = 30 A.
- (3) Measured at 25°C.

Electrical Characteristics (continued)

over operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$\Delta_{C_{IO-TO-GND}}$	Variation of channel input capacitance	Pin 4 = 0 V, $f = 1$ MHz, $V_{BIAS} = 2.5$ V, channel_x pin to GND – channel_y pin to GND ⁽³⁾		0.03	0.1	pF
V_{BR}	Break-down voltage	$I_{IO} = 1$ mA	6.5		8.5	V
I_{LEAK}	Leakage current	$V_{IO} = 2.5$ V		1	10	nA

6.6 Typical Characteristics

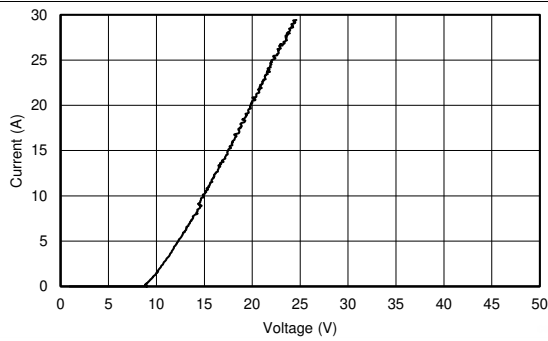


Figure 1. TLP, Data to GND

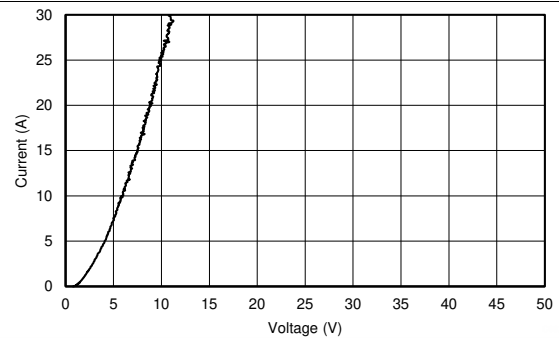


Figure 2. TLP, GND to Data

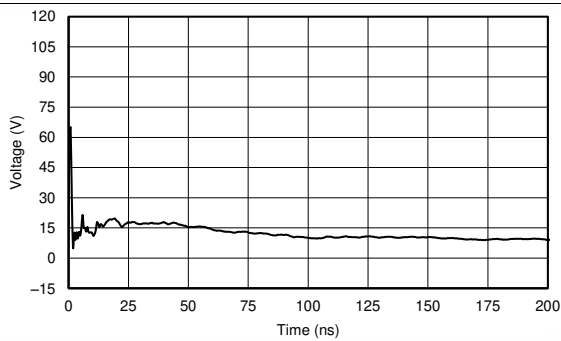


Figure 3. IEC 61000-4-2 Clamping Voltage, +8 kV Contact

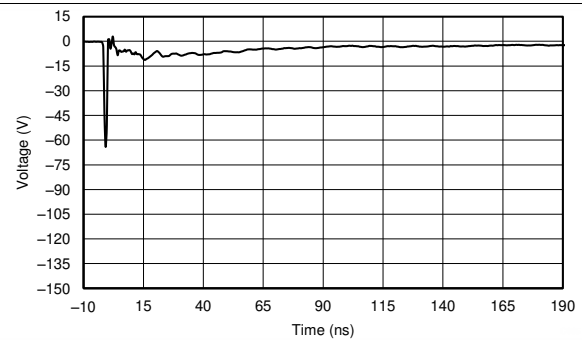
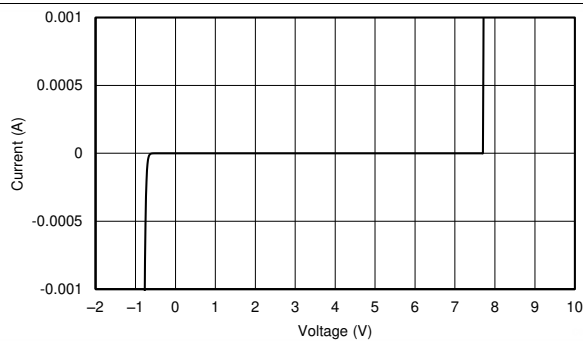
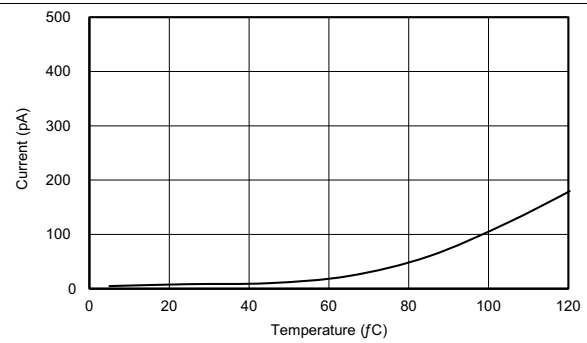


Figure 4. IEC 61000-4-2 Clamping Voltage, -8 kV Contact



$T_A = 25^\circ\text{C}$

Figure 5. IV Curve



$V_{IN} = 2.5\text{ V}$

Figure 6. I_{LEAK} vs Temperature

Typical Characteristics (continued)

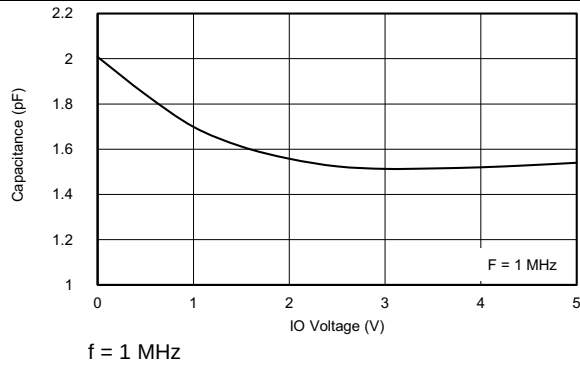


Figure 7. Capacitance Across V_{BIAS}

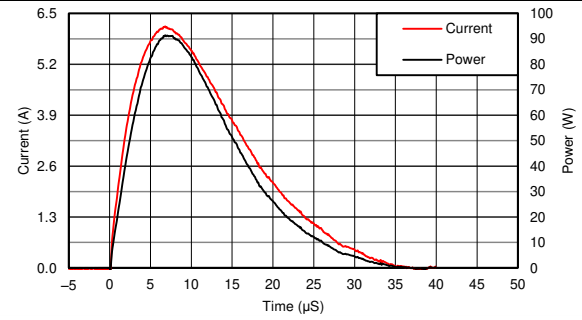


Figure 8. Surge Curve ($t_p = 8/20 \mu\text{s}$) IO to GND

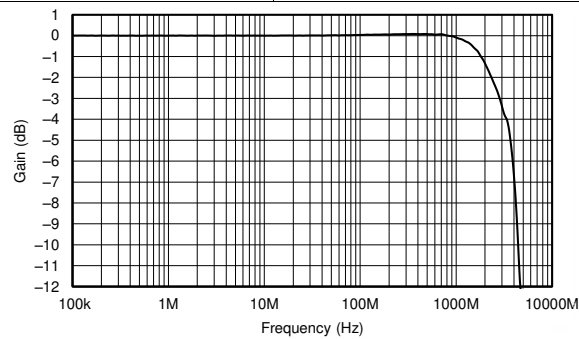


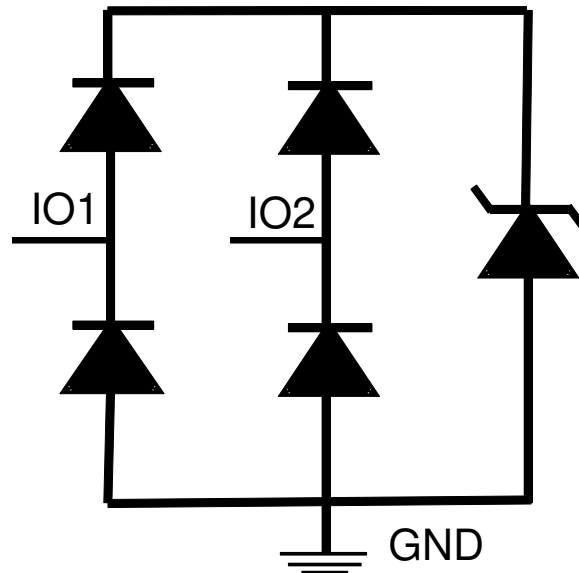
Figure 9. Insertion Loss

7 Detailed Description

7.1 Overview

The TPD2E2U06 is a dual-channel low capacitance TVS diode ESD protection device. The device offers ± 25 -kV contact and ± 30 -kV air-gap ESD protection in accordance with the IEC 61000-4-2 standard. The 1.5-pF line capacitance of the TPD2E2U06 makes the device suitable for a wide range of applications. Typical application interfaces are USB 2.0, LVDS, and I2C.

7.2 Functional Block Diagram



7.3 Feature Description

The TPD2E2U06 is a dual-channel low capacitance TVS diode ESD protection device. The device offers ± 25 -kV contact and ± 30 -kV air-gap ESD protection in accordance with the IEC 61000-4-2 standard. The 1.5-pF line capacitance of the TPD2E2U06 makes the device suitable for a wide range of applications. Typical application interfaces are USB 2.0, LVDS, and I2C.

7.3.1 IEC 61000-4-2 Level 4

The I/O pins can withstand ESD events up to ± 25 -kV contact and ± 30 -kV air. An ESD/surge clamp diverts the current to ground.

7.3.2 IO Capacitance

The capacitance between each I/O pin to ground is 1.5 pF. These capacitances support data rates in excess of 1.5 Gbps.

7.3.3 DC Breakdown Voltage

The DC breakdown voltage of each I/O pin is a minimum of 6.5 V. This ensures that sensitive equipment is protected from surges above the reverse standoff voltage of 5.5 V.

7.3.4 Ultra-Low Leakage Current

The I/O pins feature an ultra-low leakage current of 10 nA (Max) with a bias of 2.5 V.

7.3.5 Low ESD Clamping Voltage

The I/O pins feature an ESD clamp that is capable of clamping the voltage to 9.7 V ($I_{PP} = 1$ A).

Feature Description (continued)

7.3.6 Industrial Temperature Range

This device is designed to operate from -40°C to 125°C .

7.3.7 Small Easy-to-Route Package

The layout of this device makes it simple and easy to add protection to an existing layout. The package offers flow-through routing, requiring minimal modification to an existing layout.

7.4 Device Functional Modes

TPD2E2U06 is a passive integrated circuit that triggers when voltages are above V_{BR} or below the lower diodes V_{f} (-0.6 V). During ESD events, voltages as high as $\pm 30\text{ kV}$ (air) can be directed to ground via the internal diode network. Once the voltages on the protected line fall below the trigger levels of TPD2E2U06 (usually within 10's of nano-seconds) the device reverts to passive.

8 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information

TPD2E2U06 is a diode type TVS which is typically used to provide a path to ground for dissipating ESD events on hi-speed signal lines between a human interface connector and a system. As the current from ESD passes through the TVS, only a small voltage drop is present across the diode. This is the voltage presented to the protected IC. The low R_{DYN} of the triggered TVS holds this voltage, V_{CLAMP} , to a safe level for the protected IC.

8.2 Typical Application

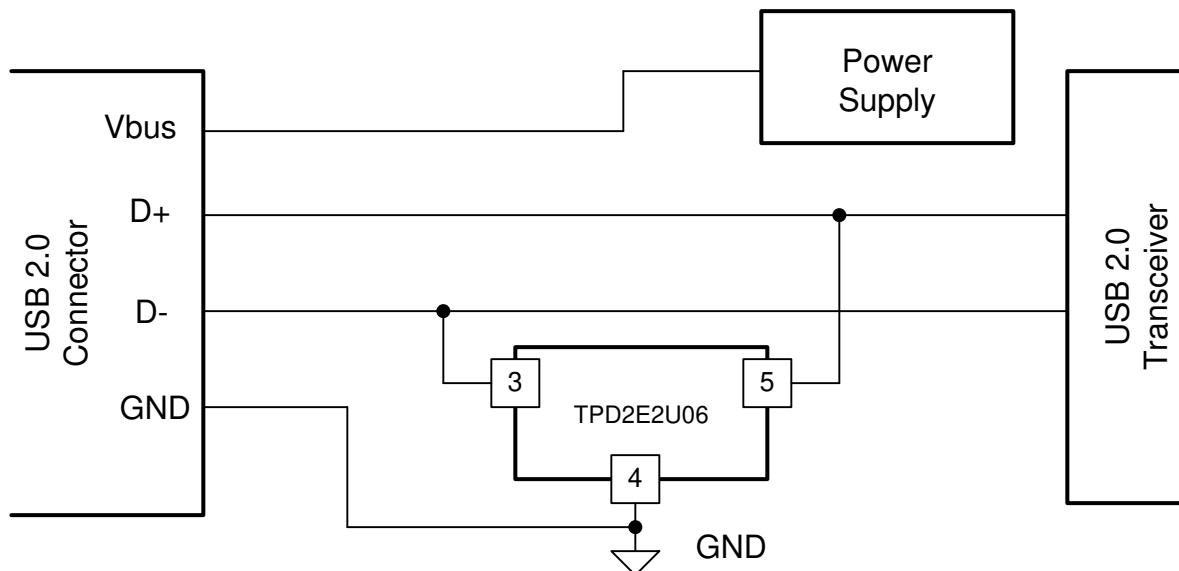


Figure 10. Typical USB Application Diagram

8.2.1 Design Requirements

For this design example, one TPD2E2U06 device will be used in a USB 2.0 application. This will provide complete port protection.

Given the USB 2.0 application, the following parameters are known.

DESIGN PARAMETER	VALUE
Signal range on Pins 3 or 5	0 V to 3.3 V
Operating Frequency	240 MHz

8.2.2 Detailed Design Procedure

To begin the design process, some parameters must be decided upon; the designer needs to know the following:

- Signal range of all the protected lines
- Operating frequency

8.2.2.1 Signal Range

The TPD2E2U06 has 2 identical protection channels for signal lines. The symmetry of the device provides flexibility when selecting which of the 2 I/O channels will protect which signal lines. Any I/O will support a signal range of 0 to 5.5 V.

8.2.2.2 Operating Frequency

The TPD2E2U06 has a capacitance of 1.5 pF (Typ), supporting USB 2.0 data rates.

8.2.3 Application Curves

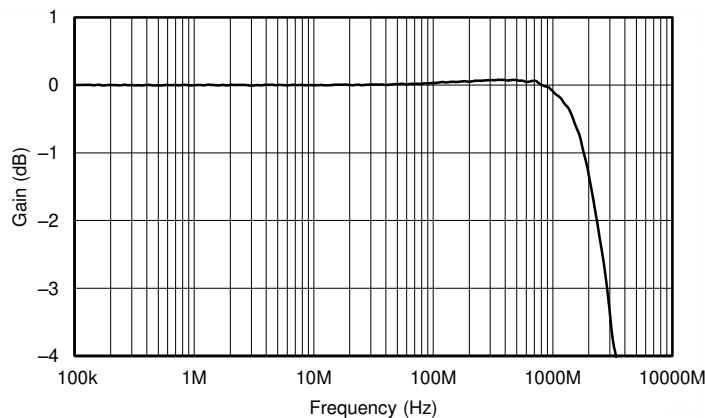


Figure 11. Insertion Loss Graph

9 Power Supply Recommendations

This device is a passive ESD protection device and there is no need to power it. Care should be taken to make sure that the maximum voltage specifications for each line are not violated.

10 Layout

10.1 Layout Guidelines

- The optimum placement is as close to the connector as possible.
 - EMI during an ESD event can couple from the trace being struck to other nearby unprotected traces, resulting in early system failures.
 - The PCB designer needs to minimize the possibility of EMI coupling by keeping any unprotected traces away from the protected traces which are between the TVS and the connector.
- Route the protected traces as straight as possible.
- Eliminate any sharp corners on the protected traces between the TVS and the connector by using rounded corners with the largest radii possible.
 - Electric fields tend to build up on corners, increasing EMI coupling.

10.2 Layout Example

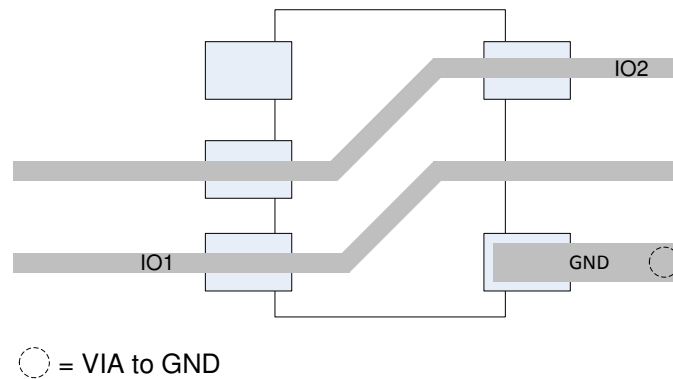


Figure 12. Routing with DRL Package

11 デバイスおよびドキュメントのサポート

11.1 商標

E2E is a trademark of Texas Instruments.

I²C is a trademark of NXP Semiconductors.

All other trademarks are the property of their respective owners.

11.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の「アラートを受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

11.3 サポート・リソース

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

11.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPD2E2U06DCKR	Active	Production	SC70 (DCK) 3	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	1GH
TPD2E2U06DCKR.B	Active	Production	SC70 (DCK) 3	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1GH
TPD2E2U06DCKRG4.B	Active	Production	SC70 (DCK) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1GH
TPD2E2U06DRLR	Active	Production	SOT-5X3 (DRL) 5	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DT
TPD2E2U06DRLR.B	Active	Production	SOT-5X3 (DRL) 5	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DT
TPD2E2U06DRLRG4.B	Active	Production	SOT-5X3 (DRL) 5	4000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	DT

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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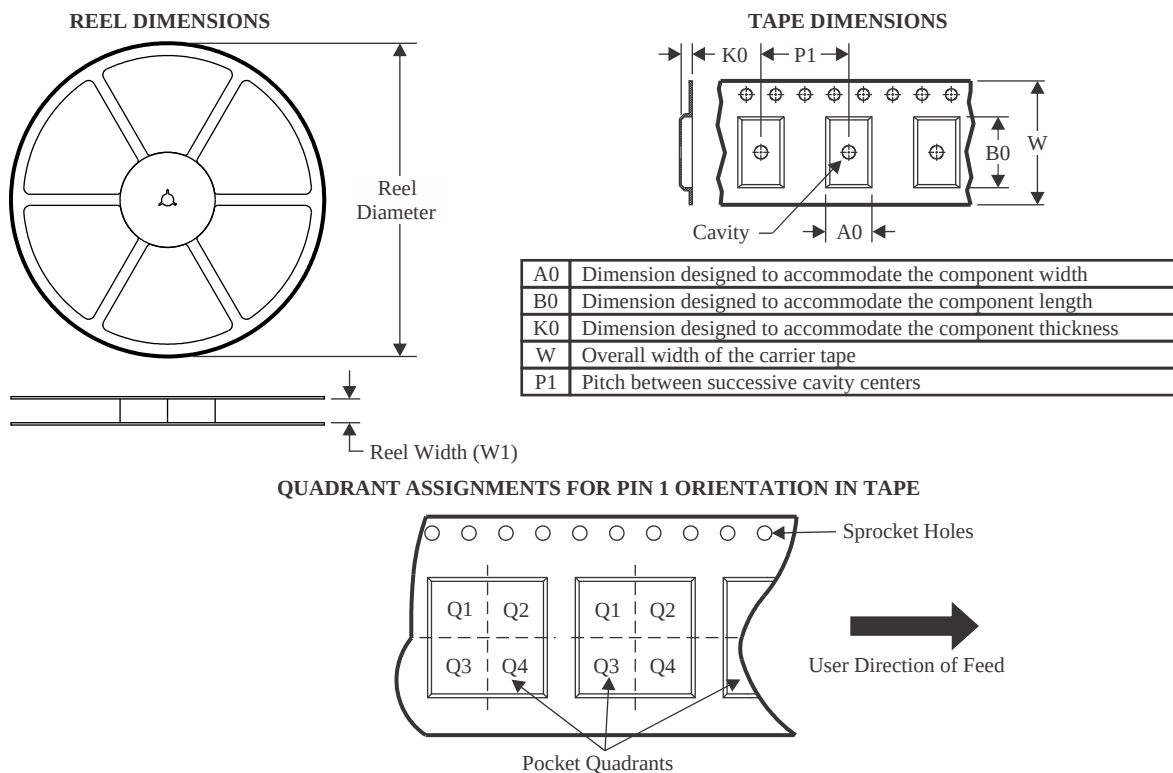
OTHER QUALIFIED VERSIONS OF TPD2E2U06 :

- Automotive : [TPD2E2U06-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

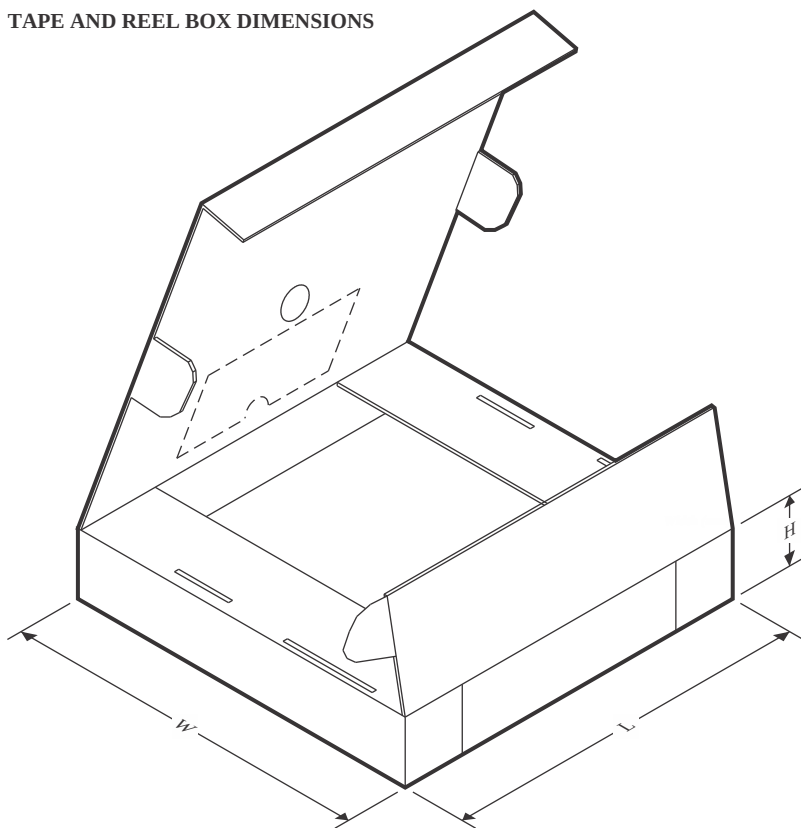
TAPE AND REEL INFORMATION



*All dimensions are nominal

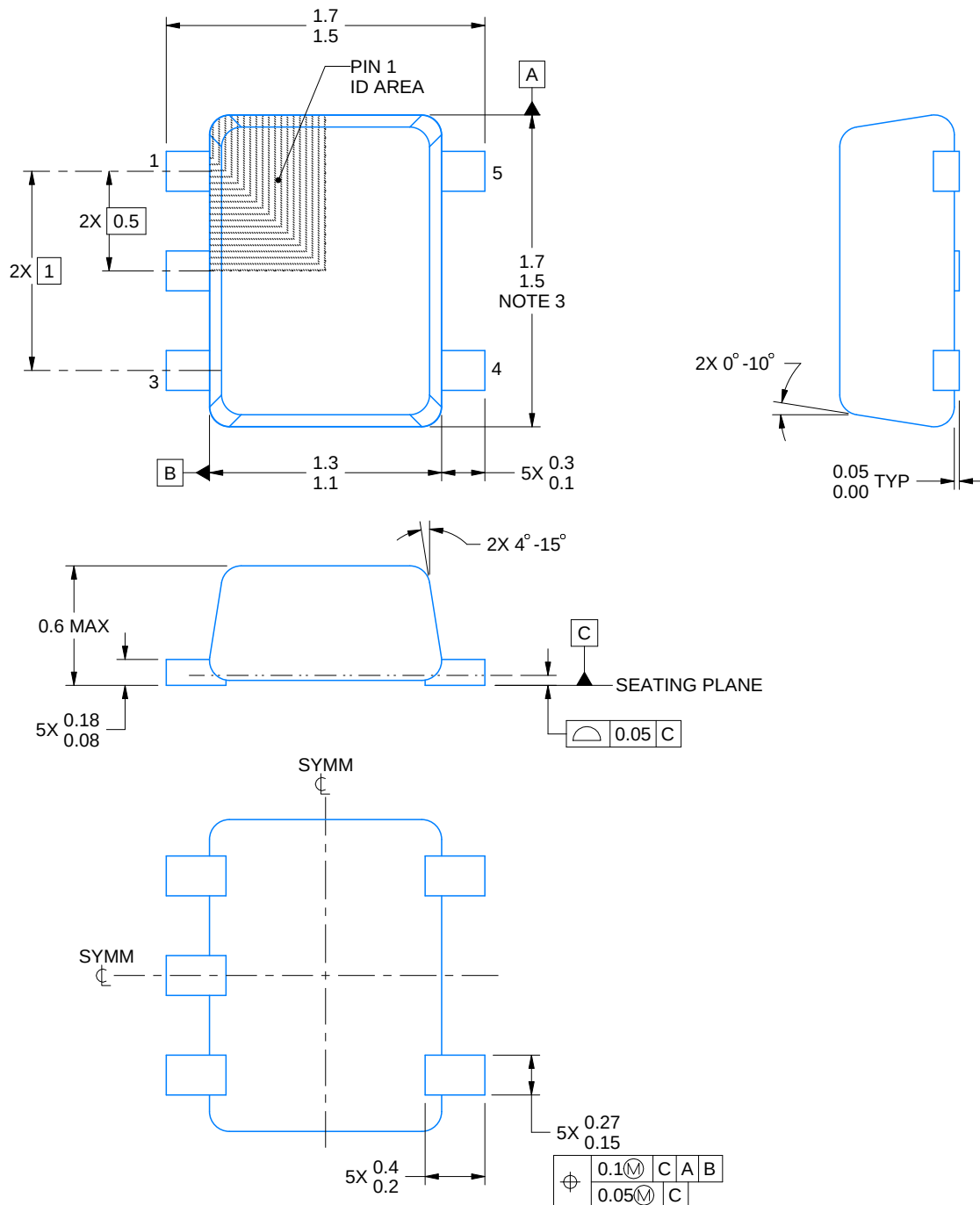
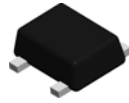
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD2E2U06DCKR	SC70	DCK	3	3000	180.0	8.4	2.3	2.75	1.2	4.0	8.0	Q3
TPD2E2U06DRLR	SOT-5X3	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD2E2U06DCKR	SC70	DCK	3	3000	210.0	185.0	35.0
TPD2E2U06DRLR	SOT-5X3	DRL	5	4000	183.0	183.0	20.0



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NOTES:

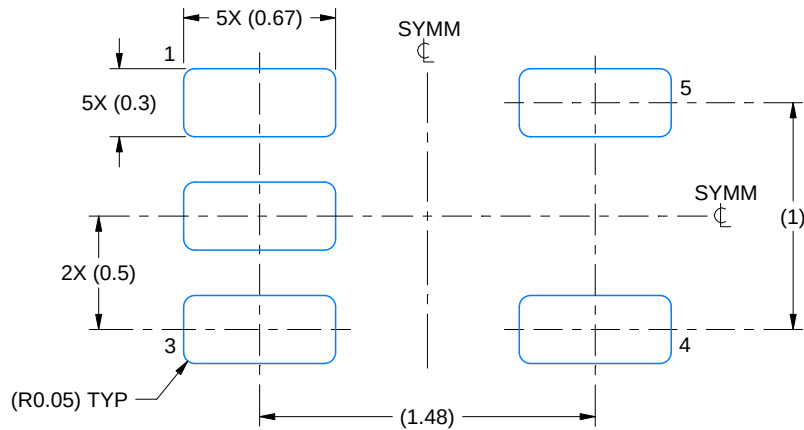
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD-1

EXAMPLE BOARD LAYOUT

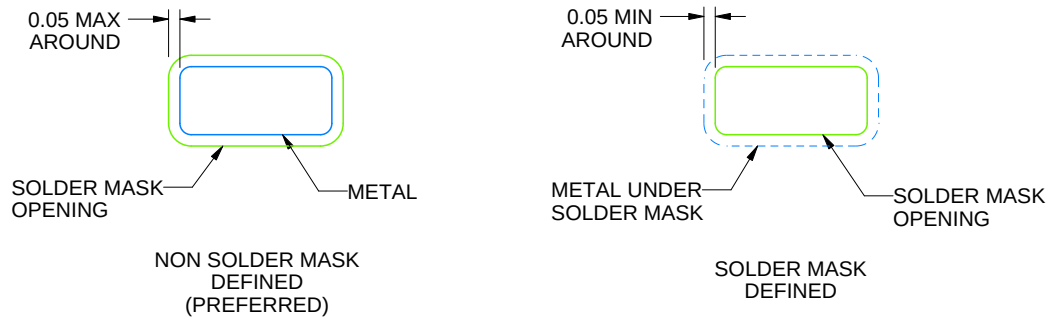
DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

4220753/E 11/2024

NOTES: (continued)

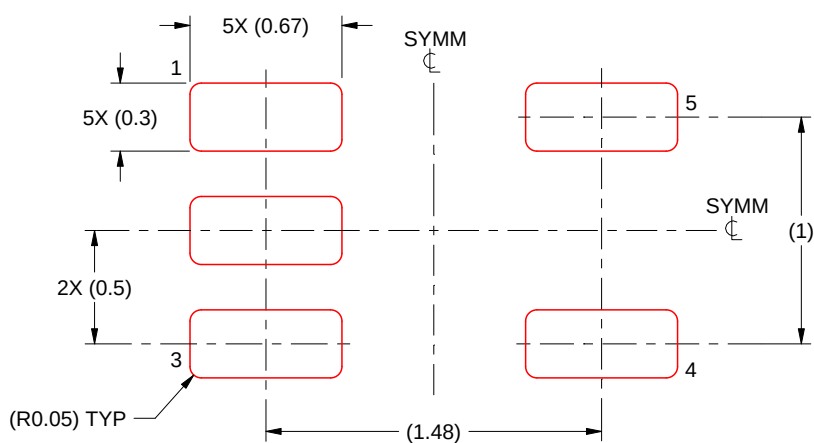
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DRL0005A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

4220753/E 11/2024

NOTES: (continued)

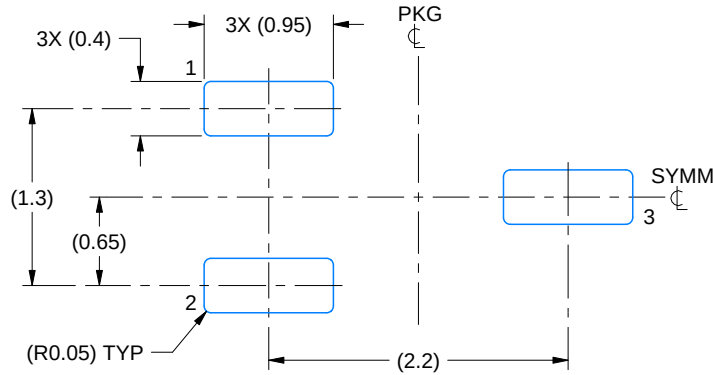
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

EXAMPLE BOARD LAYOUT

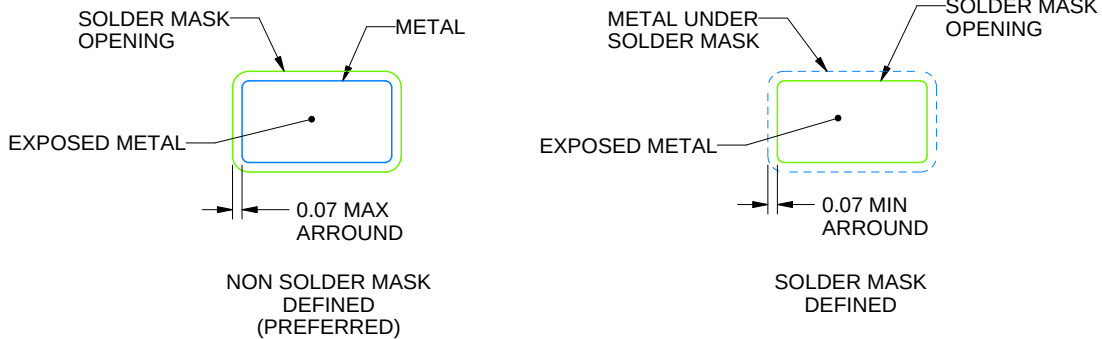
DCK0003A

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

4220745/F 11/2024

NOTES: (continued)

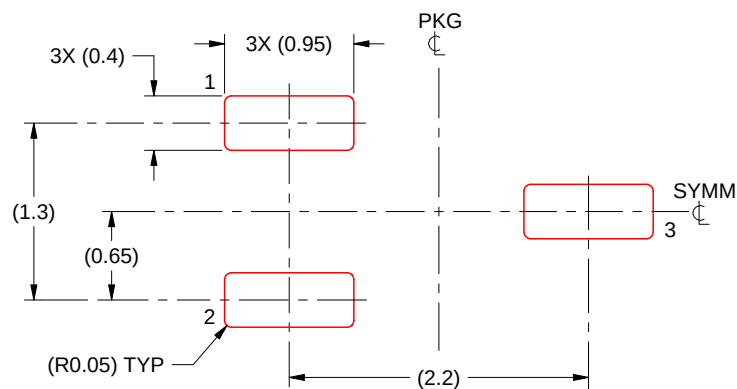
4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCK0003A

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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